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Octal D-type Flip-Flops (with Clear)



ADE-205-482 (Z) 1st. Edition Sep. 2000

Description

This device contains 8 master-slave flip-flops with a common clock and common clear. Data on the D input having the specified setup and hold times is transferred to the Q output on the low to high transition of the clock input. The clear input when low, sets all outputs to a low state.

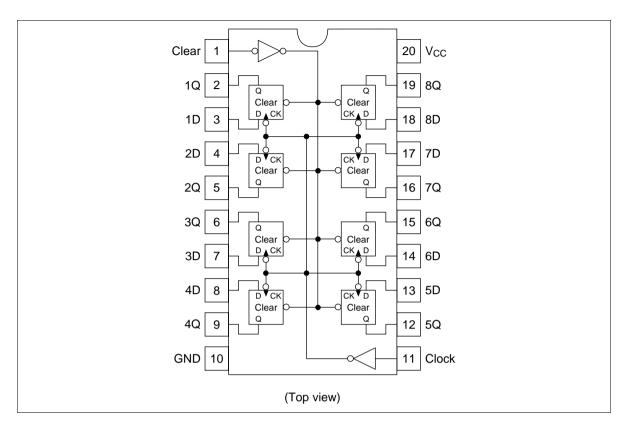
Features

- High Speed Operation: t_{pd} (Clock to Q) = 18 ns typ (C_L = 50 pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2 \text{ to } 6 \text{ V}$
- Low Input Current: 1 µA max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max (Ta = 25°C)

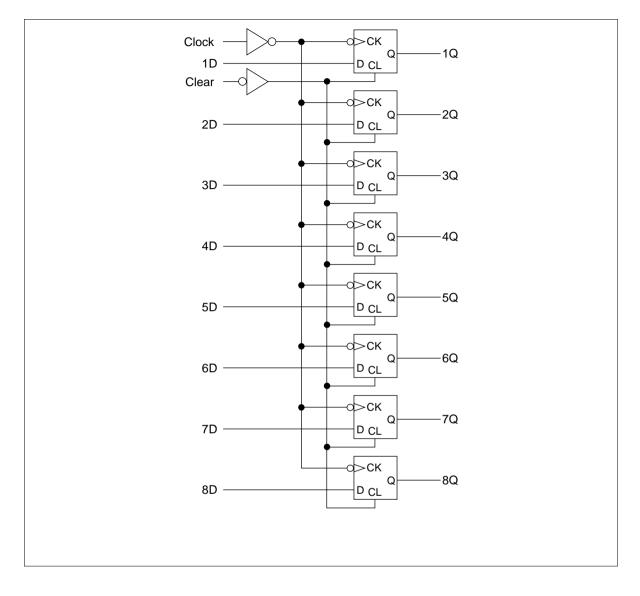
Inputs		Outputs		
Clear	Clock	D	Q	
L	Х	Х	L	
Н		Н	Н	
Н		L	L	
Н	L	Х	No change	
Н		Х	No change	

Function Table

Pin Arrangement



Logic Diagram



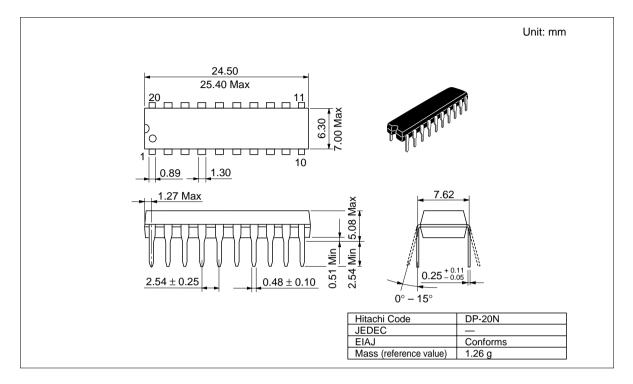
DC Characteristics

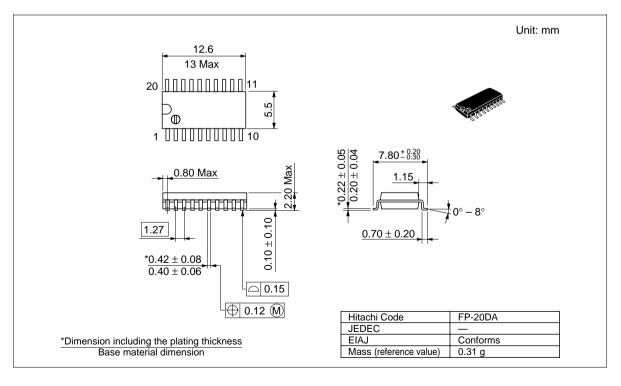
			Ta =	: 25°C)	Ta = - +85°0	-40 to C			
ltem	Symbol	V _{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Condition	ns
Input voltage	V _{IH}	2.0	1.5			1.5	_	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—	_		
	VIL	2.0		_	0.5	—	0.5	V		
		4.5			1.35		1.35	_		
		6.0			1.8	_	1.8	_		
Output voltage	V _{OH}	2.0	1.9	2.0	_	1.9	—	V	$Vin = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -20 \ \mu A$
		4.5	4.4	4.5	—	4.4	—	_		
		6.0	5.9	6.0	_	5.9	—	_		
		4.5	4.18		_	4.13	—	_		I _{он} = -4 mА
		6.0	5.68	_	—	5.63	—			I _{он} = -5.2 mА
	V _{OL}	2.0	_	0.0	0.1	_	0.1	V	$Vin = V_{IH} \text{ or } V_{IL}$	$I_{OL} = 20 \ \mu A$
		4.5	_	0.0	0.1		0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5		_	0.26		0.33	_		$I_{OL} = 4 \text{ mA}$
		6.0		_	0.26		0.33	_		I _{oL} = 5.2 mA
Input current	lin	6.0			±0.1		±1.0	μΑ	Vin = V _{cc} or GN	ND
Quiescent supply current	I _{cc}	6.0	—		4.0	—	40	μA	Vin = V _{cc} or GN	ND, lout = $0 \mu A$

			Ta = 25°C		Ta = –40 to +85°C				
Item	Symbol	V _{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Conditions
Maximum clock	\mathbf{f}_{\max}	2.0	_	_	6	—	5	MHz	
frequency		4.5	_	_	30	_	24	_	
		6.0		_	35		28	_	
Propagation delay	t _{PHL}	2.0		_	145		180	ns	Clock to Q
time		4.5		18	29		36	_	
		6.0		_	25		31	_	
	t _{PLH}	2.0		_	145		180	ns	_
		4.5	_	18	29	_	36	_	
		6.0		_	25		31	_	
	t _{PHL}	2.0		_	145		180	ns	Clear to Q
		4.5		15	29	_	36	_	
		6.0		_	25	_	31	_	
Setup time	t _{su}	2.0	100	_	_	125	—	ns	Data to clock
		4.5	20	2		25	—	_	
		6.0	17	_	_	21	—	_	
Hold time	t _h	2.0	5	_		5	—	ns	Clock to data
		4.5	5	0		5	—	_	
		6.0	5			5	—	_	
Removal time	t _{rem}	2.0	100	_		125	—	ns	Clear to clock
		4.5	20	-1		25	_	_	
		6.0	17	_		21	_	_	
Pulse width	t _w	2.0	80	_		100	—	ns	Clock, clear
		4.5	16	8		20	_	_	
		6.0	14	_		17	_	_	
Output rise/fall	t _{TLH}	2.0		_	75		95	ns	
time	t_{THL}	4.5		5	15		19	-	
		6.0	_	_	13	—	16	-	
Input capacitance	Cin		—	5	10	—	10	pF	

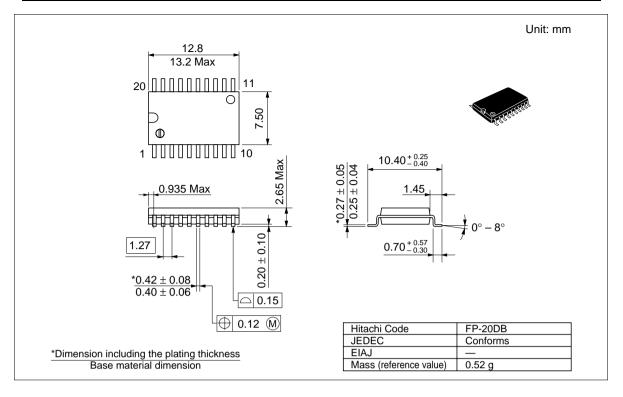
AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

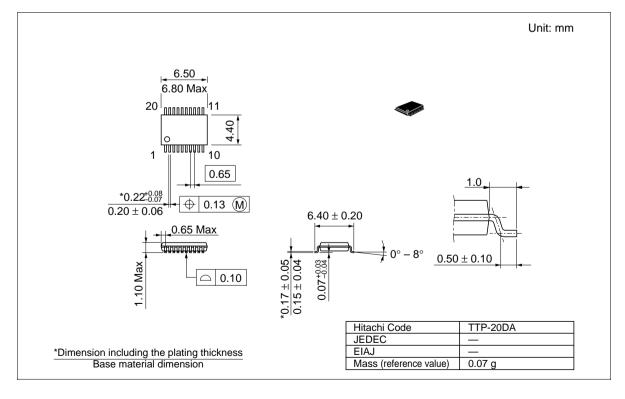
Package Dimensions











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